

DC Copper Plating for Thick Panel

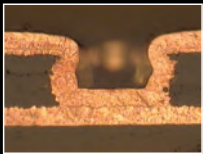
厚板高纵横比 电镀铜技术

Next Generation of Thick Panel Copper Plating Technology

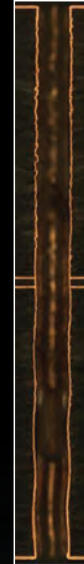
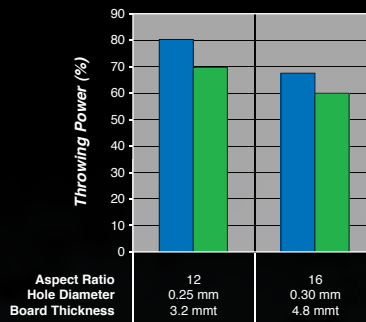
A latest technology is under developed for thick panel plating, which provides better throwing power under a basis of 10%~20% higher current density than existing product. Obviously, it helps to increase plating efficiency and obtainable higher productivity without any required equipment investment.

最新一代的厚板电镀技术正在开发中，在相对于现有产品高于10%~20%电流密度的基础上，它将能提供较佳的通孔贯孔能力。显而易见的，它有助于提高电镀效率与产能且不需任何设备的投资。

- High throwing power
高通孔贯孔能力
 - at higher plating current density
于高电流密度下
 - on high aspect ratio boards
于高纵横度板
 - on microvia
于微盲孔电镀
- Microvia plating capability
可同时兼顾微盲孔电镀
- Full analysis system by CVS
可使用 CVS分析所有添加剂
- Excellent thermal reliability
优越的热信赖度



Via diameter:
6 mil
Via depth:
4 mil
CD:
6 ASF



Hole diameter:
0.5 mm
Panel thickness:
8 mm
CD:
12 ASF

ELECTROPOSIT™ 1000 (SHARP) Process

High Aspect Ratio Plating System (SHARP) is designed for reliable through-hole plating of thick multi-layer printed circuit boards. Dow Electronic Materials can provide this process for plating through-holes with aspect ratios greater than 16:1. The SHARP process consists of ELECTROPOSIT™ 1000 plating additives and a specially-developed high acid, low copper plating bath. This combination gives excellent throwing power at plating rates not possible with other processes.

高纵横比电镀系统 (SHARP) 是专为多层厚板通孔电镀所开发的高可靠性制程。陶氏电子材料可以提供此制程来电镀孔纵横高于 16:1 的通孔电镀。SHARP 制程包含了 Electroposit 1000 电镀添加剂与特别开发的高酸，低铜镀液。这种组合表现出其他电镀制程无法比拟的优越通孔贯孔能力。

Advantage of ELECTROPOSIT™ 1000 Process

ELECTROPOSIT 1000 具备以下优越的特性

- Excellent throwing power, surface distribution, and leveling capabilities
优秀的通孔贯孔能力，表面均匀度与整平能力
- Compatibility with both panel and pattern plating processing
可适用于板电或图形电镀流程
- Utilizes conventional equipment
可使用于传统龙门式电镀设备
- Superior thermal stress resistance—meets or exceeds MIL-P-55110 D
优越的热应力，并通过 MIL-P-55110 D 规范
- Ease of control and straight forward Hull Cell interpretation
易于控制并可直接用哈氏槽控管



Hole diameter:
0.66 mm
Panel thickness:
6.6 mm
CD:
6 ASF



Electronic Materials